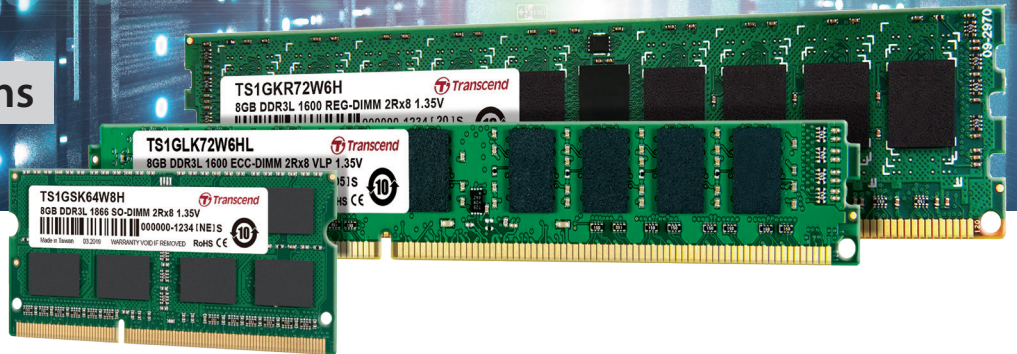


Embedded Solutions



DRAM Modules DDR3

Transcend's DDR3 DRAM modules operate at a nominal voltage of 1.5V or 1.35V, offering exceptional clock speeds to cater to the demands of the embedded industry. The modules are available in multiple form factors and technologies, such as ECC and wide-temperature support. All components are of the highest quality, having been sourced directly from the world's first-tier supplier of DRAM chips and stringently tested for unparalleled compatibility, reliability, and performance.

Features

- JEDEC standard 1.5V ± 0.075V power supply
- Low Voltage models: JEDEC standard 1.35V (1.28V~1.45V) power supply
- 8 bit pre-fetch
- Burst Length: 4, 8
- Internal calibration through ZQ pin
- On-die termination with ODT pin
- Serial presence detect with EEPROM
- 100% tested for stability, compatibility and performance

Advanced Technologies



Anti-Sulfur Technology



Corner Bond & Underfill



Conformal Coating





Wide Temperature



30 µm Gold Finger

DDR3 ECC DIMMs

Module Type	DDR3	
	ECC Long-DIMM	ECC SO-DIMM
Product Image		
Standard	JEDEC	
Speed	1600/1333 Mbps	
Capacity	2GB~8GB	
Voltage	Standard voltage: 1.5V Low voltage: 1.35V	
Pin Count	Long-DIMM: 240 pin	SO-DIMM: 204 pin
PCB Height*	Standard: 1.18 inches Very Low Profile: 0.74 inches	
PCB Gold Finger Thickness	30μ"	
Anti-Sulfuration	Default	
Operating Temperature	Standard Temperature: 0°C~ 85°C Wide Temperature: -40°C~ 85°C	

Ordering Information

DDR3-1600 ECC Long-DIMM

Capacity	Component Composition	Rank x Org.	Standard (1.5V)	Wide Temp. (-40°C~ 85°C)	Low Voltage (1.35V)	Low Voltage + Wide Temp.
2GB	(128Mx8)x18	2Rx8	TS256MLK72V6U	TS256MLK72V6U-I	TS256MLK72W6U	TS256MLK72W6U-I
2GB	(256Mx8)x9	1Rx8	TS256MLK72V6N	TS256MLK72V6N-I	TS256MLK72W6N	TS256MLK72W6N-I
4GB	(256Mx8)x18	2Rx8	TS512MLK72V6N	TS512MLK72V6N-I	TS512MLK72W6N	TS512MLK72W6N-I
4GB	(512Mx8)x9	1Rx8	TS512MLK72V6H	TS512MLK72V6H-I	TS512MLK72W6H	TS512MLK72W6H-I
8GB	(512Mx8)x18	2Rx8	TS1GLK72V6H	TS1GLK72V6H-I	TS1GLK72W6H	TS1GLK72W6H-I

DDR3-1600 ECC Long-DIMM

Capacity	Component Composition	Rank x Org.	Very Low Profile (VLP)
4GB	(512Mx8)x9	1Rx8	TS512MLK72W6HL
8GB	(512Mx8)x18	2Rx8	TS1GLK72W6HL

* DDR3 ECC Long-DIMM VLP modules (0.74 inches) are also available.

DDR3-1600 ECC SO-DIMM

Capacity	Component Composition	Rank x Org.	Standard (1.5V)	Wide Temp. (-40°C~ 85°C)	Low Voltage (1.35V)	Low Voltage + Wide Temp.
2GB	(256Mx8)x9	1Rx8	TS256MSK72V6N	TS256MSK72V6N-I	TS256MSK72W6N	TS256MSK72W6N-I
4GB	(256Mx8)x18	2Rx8	TS512MSK72V6N	TS512MSK72V6N-I	-	TS512MSK72W6N-I
4GB	(512Mx8)x9	1Rx8	TS512MSK72V6H	TS512MSK72V6H-I	TS512MSK72W6H	TS512MSK72W6H-I
8GB	(512Mx8)x18	2Rx8	TS1GSK72V6H	TS1GSK72V6H-I	TS1GSK72W6H	TS1GSK72W6H-I

DDR3-1333 ECC Long-DIMM

Capacity	Component Composition	Rank x Org.	Standard (1.5V)	Wide Temp. (-40°C~ 85°C)	Low Voltage (1.35V)	Low Voltage + Wide Temp.
2GB	(128Mx8)x18	2Rx8	TS256MLK72V3U	-	-	-
2GB	(256Mx8)x9	1Rx8	TS256MLK72V3N	-	-	-
4GB	(256Mx8)x18	2Rx8	TS512MLK72V3N	-	-	-
8GB	(512Mx8)x18	2Rx8	TS1GLK72V3H	-	-	-

DDR3-1333 ECC SO-DIMM

Capacity	Component Composition	Rank x Org.	Standard (1.5V)	Wide Temp. (-40°C~ 85°C)	Low Voltage (1.35V)	Low Voltage + Wide Temp.
2GB	(256Mx8)x9	1Rx9	TS256MSK72V3N	TS256MSK72V3N-I	TS256MSK72W3N	-
4GB	(256Mx8)x18	2Rx8	TS512MSK72V3N	TS512MSK72V3N-I	-	-
4GB	(512Mx8)x9	1Rx8	-	-	TS512MSK72W3H	-
8GB	(512Mx8)x18	2Rx8	-	TS1GSK72V3H-I	TS1GSK72W3H	-

* DDR3 ECC Long-DIMM VLP modules (0.74 inches) are also available.